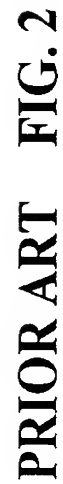


PRIOR ART FIG. 1



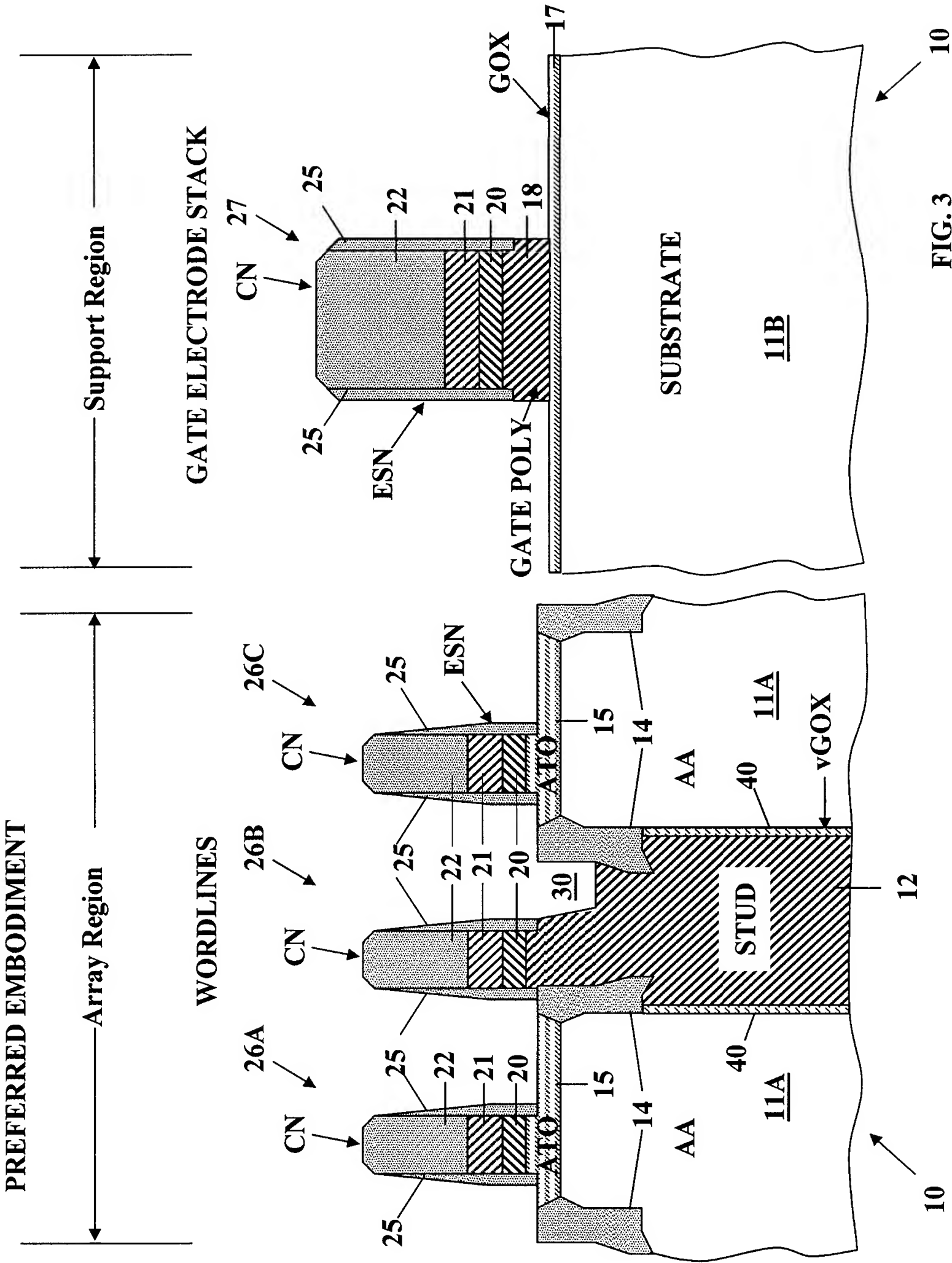
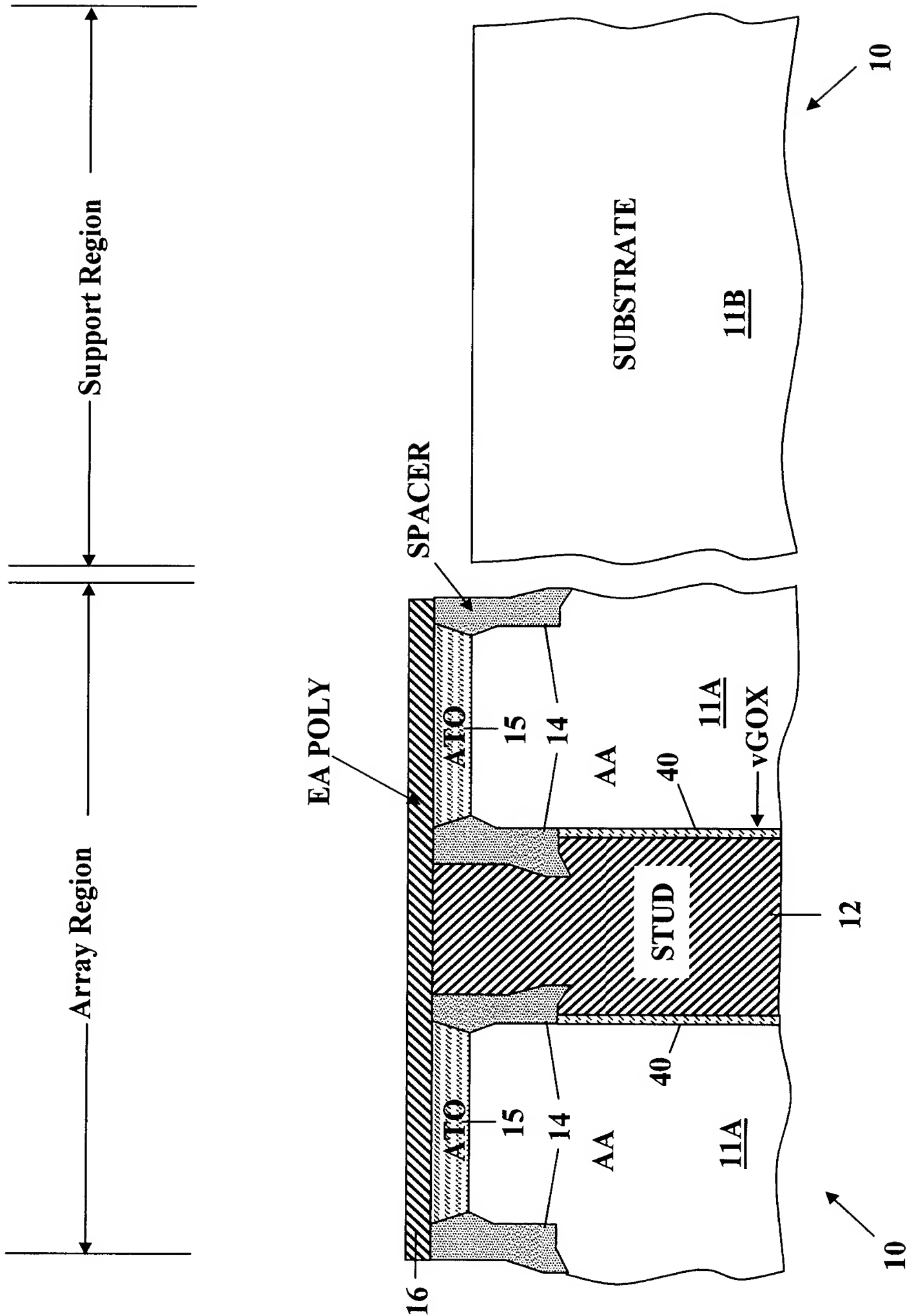


FIG. 3

1. TOE (TOP OXIDE EARLY) PROCESS FOR ATO (ARRAY REGION TOP OXIDE)



• Post ES/EA process(prior art)

FIG. 4

## 2. GATE OXIDATION

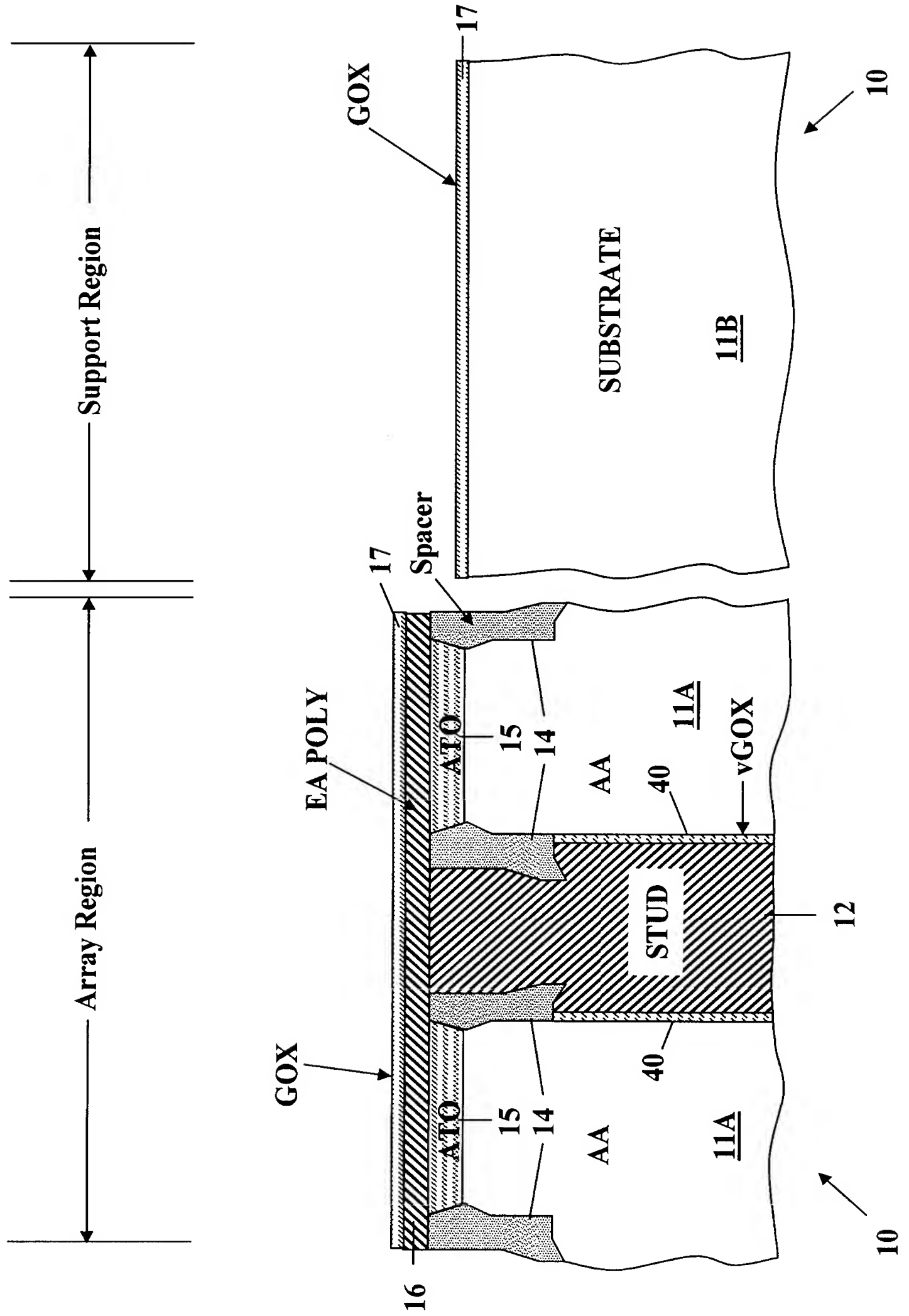
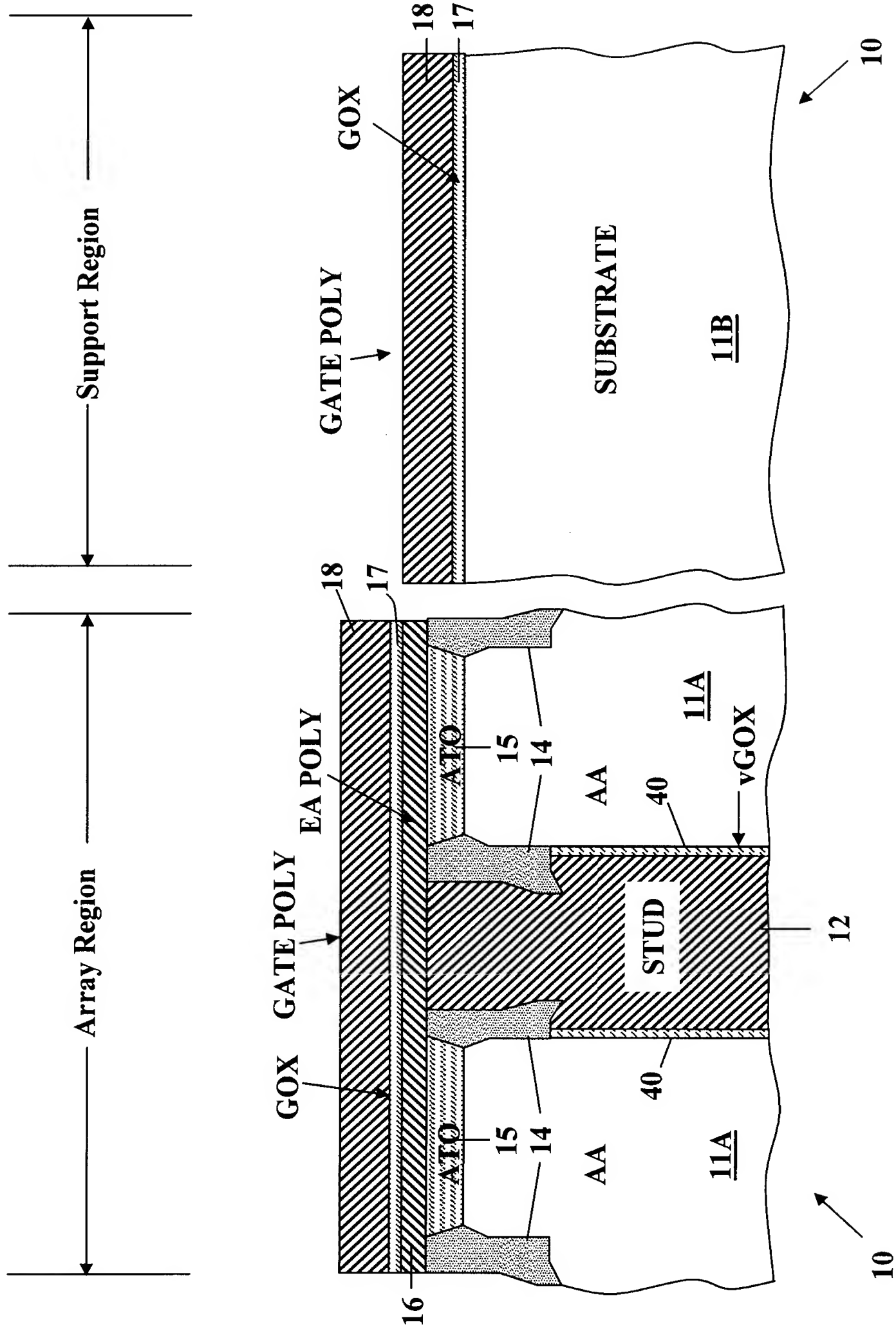


FIG. 5

### 3. THICK GATE POLYSILICON DEPOSITION



# 4. BLOCKING MASK AT SUPPORT REGION

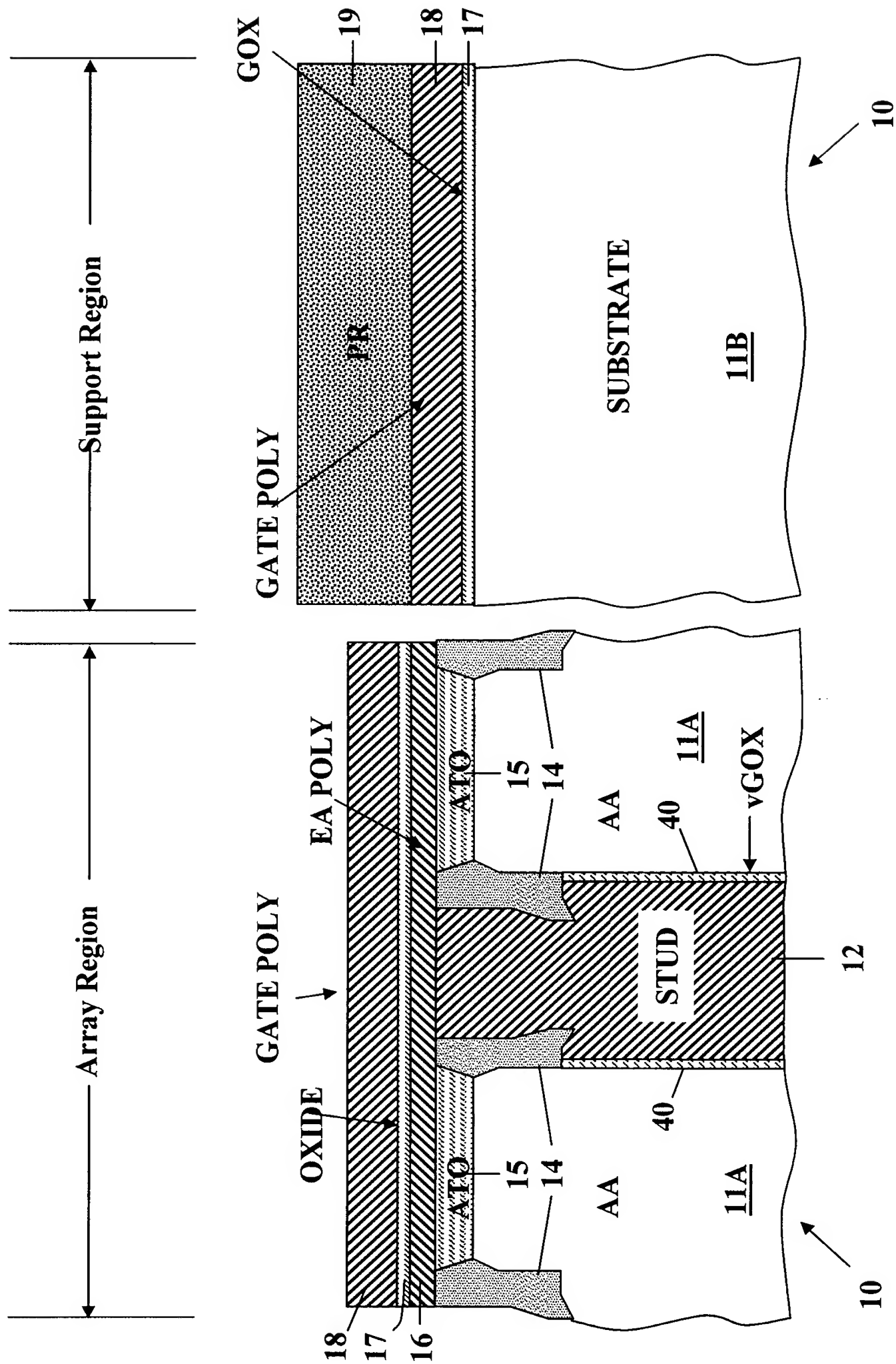
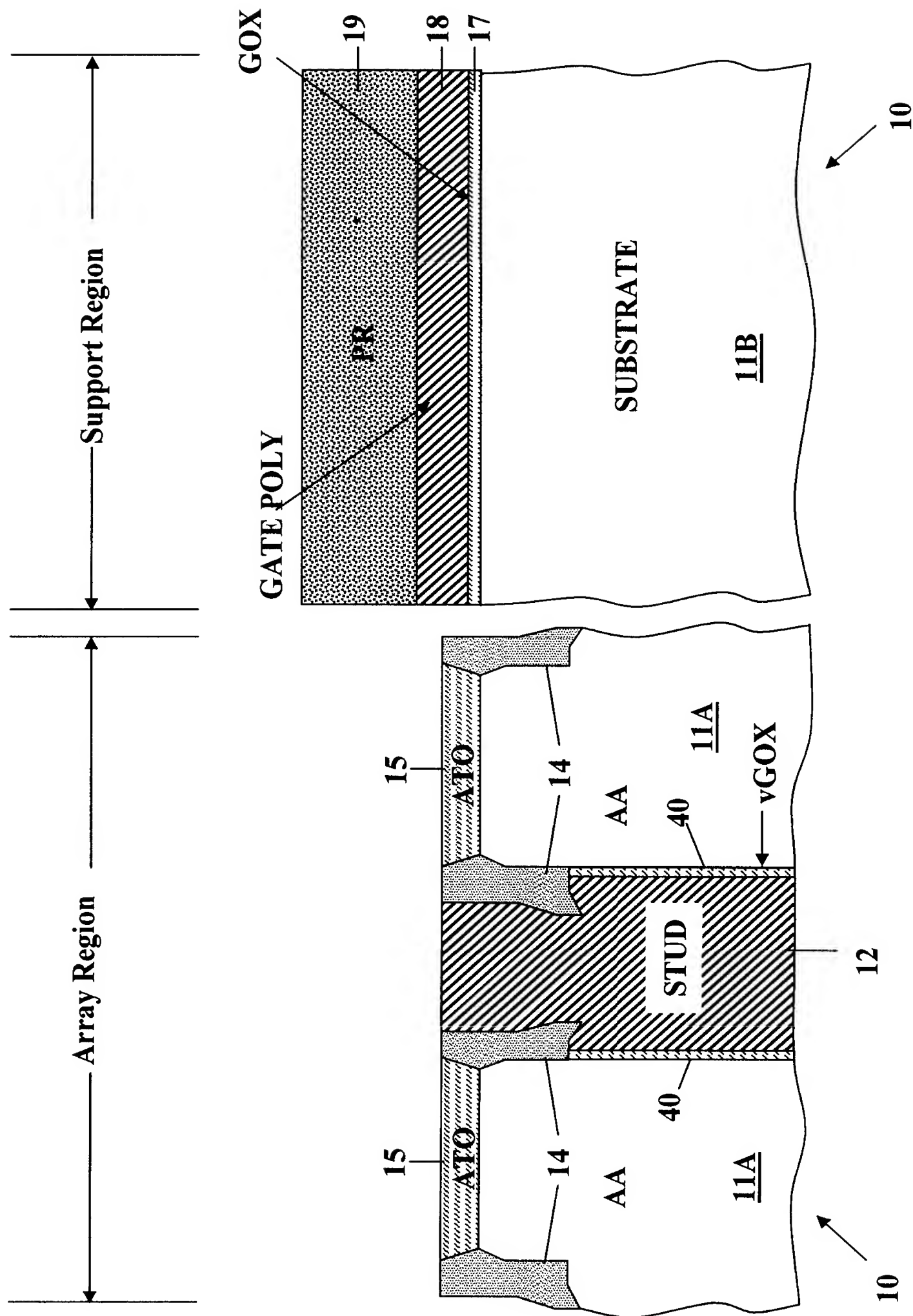


FIG. 7

## 5. POLYSILICON REMOVAL FROM ARRAY REGION





# 6. PHOTORESIST STRIP

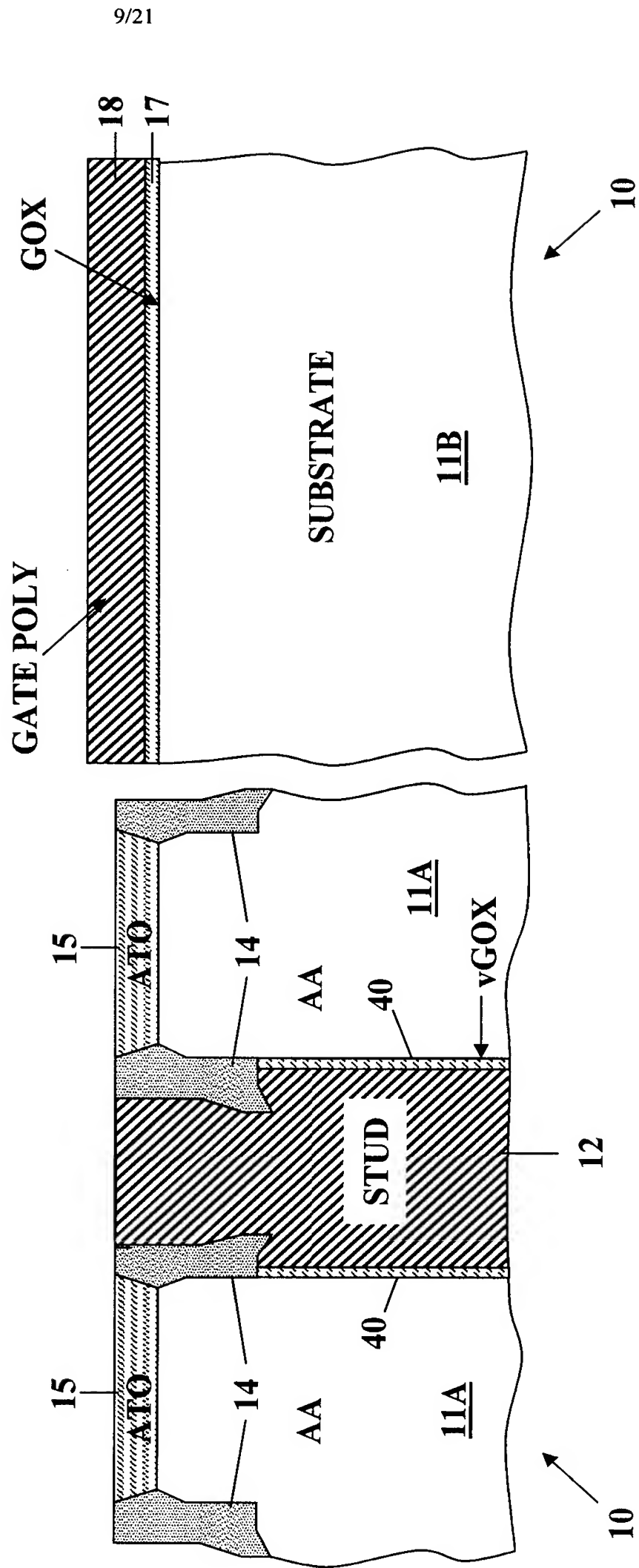
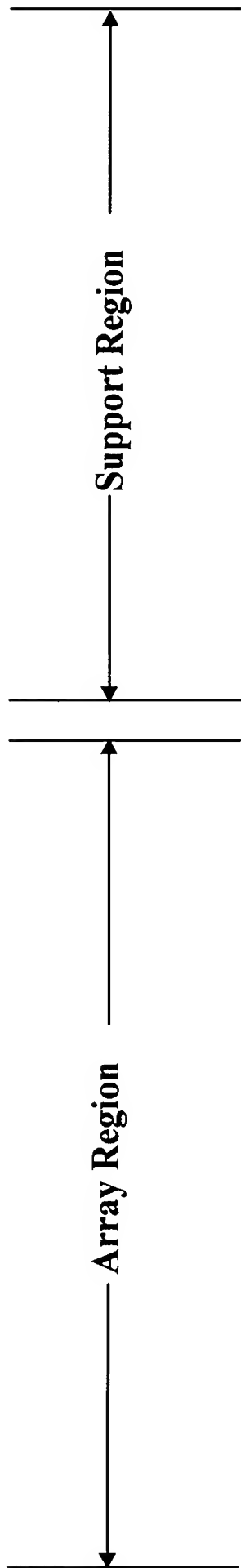


FIG. 9

# 7. PRECLEANING AND THIN POLYSILICON DEPOSITION

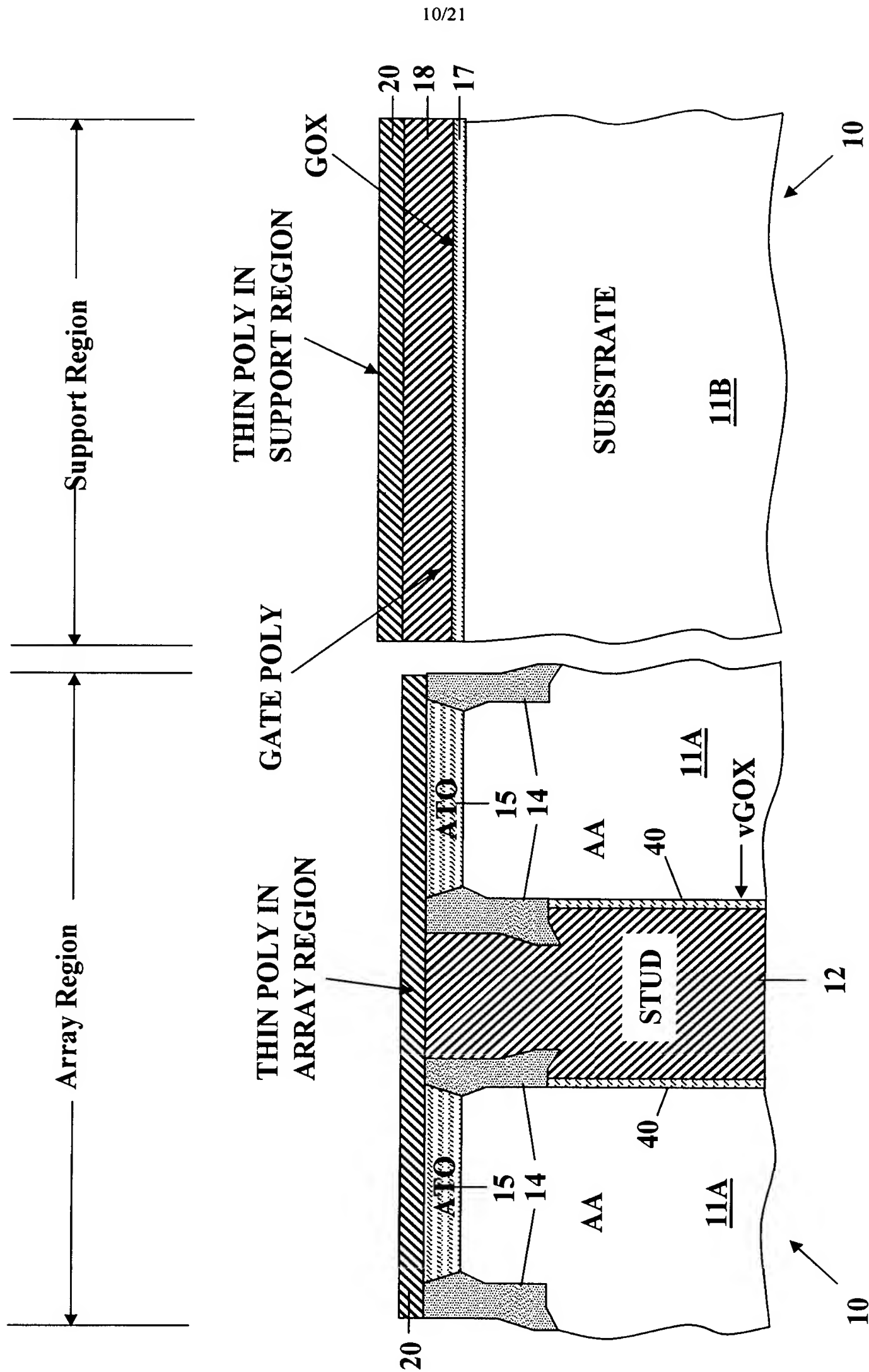
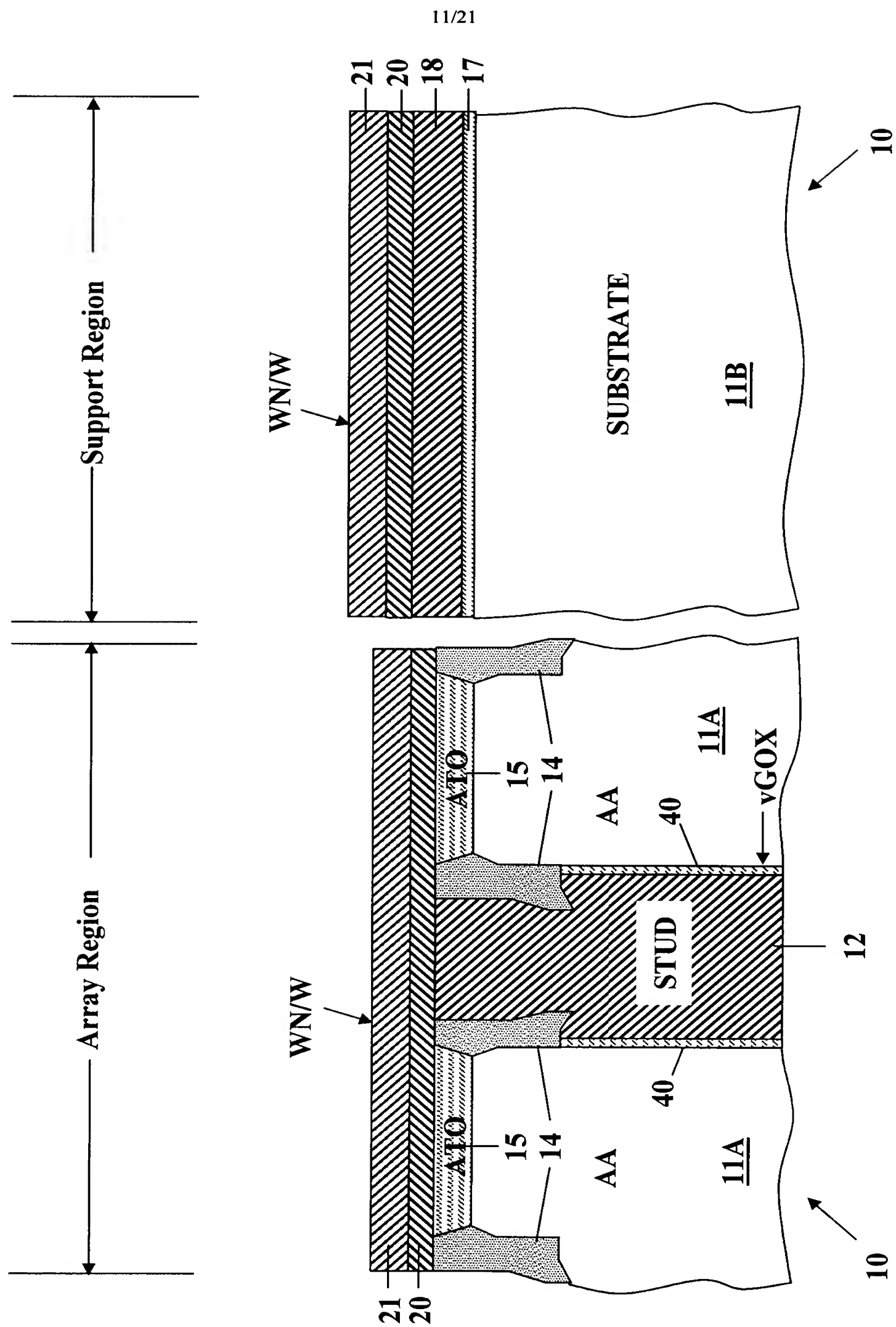


FIG. 10

## 8. BARRIER AND W DEPOSITION



**FIG. 11**

# 9. CAPPING NITRIDE DEPOSITION

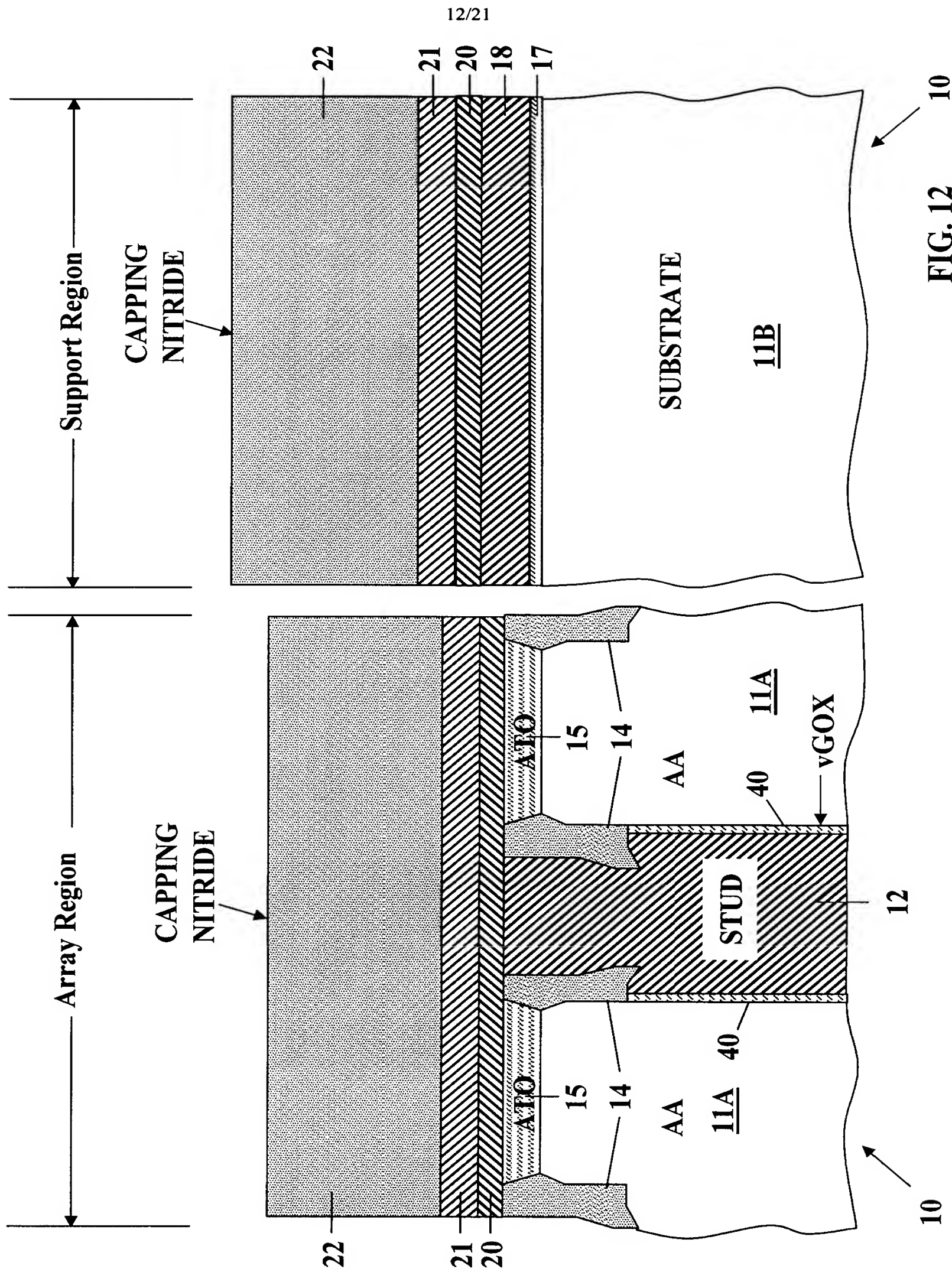


FIG. 12

10. GATE PATTERNING

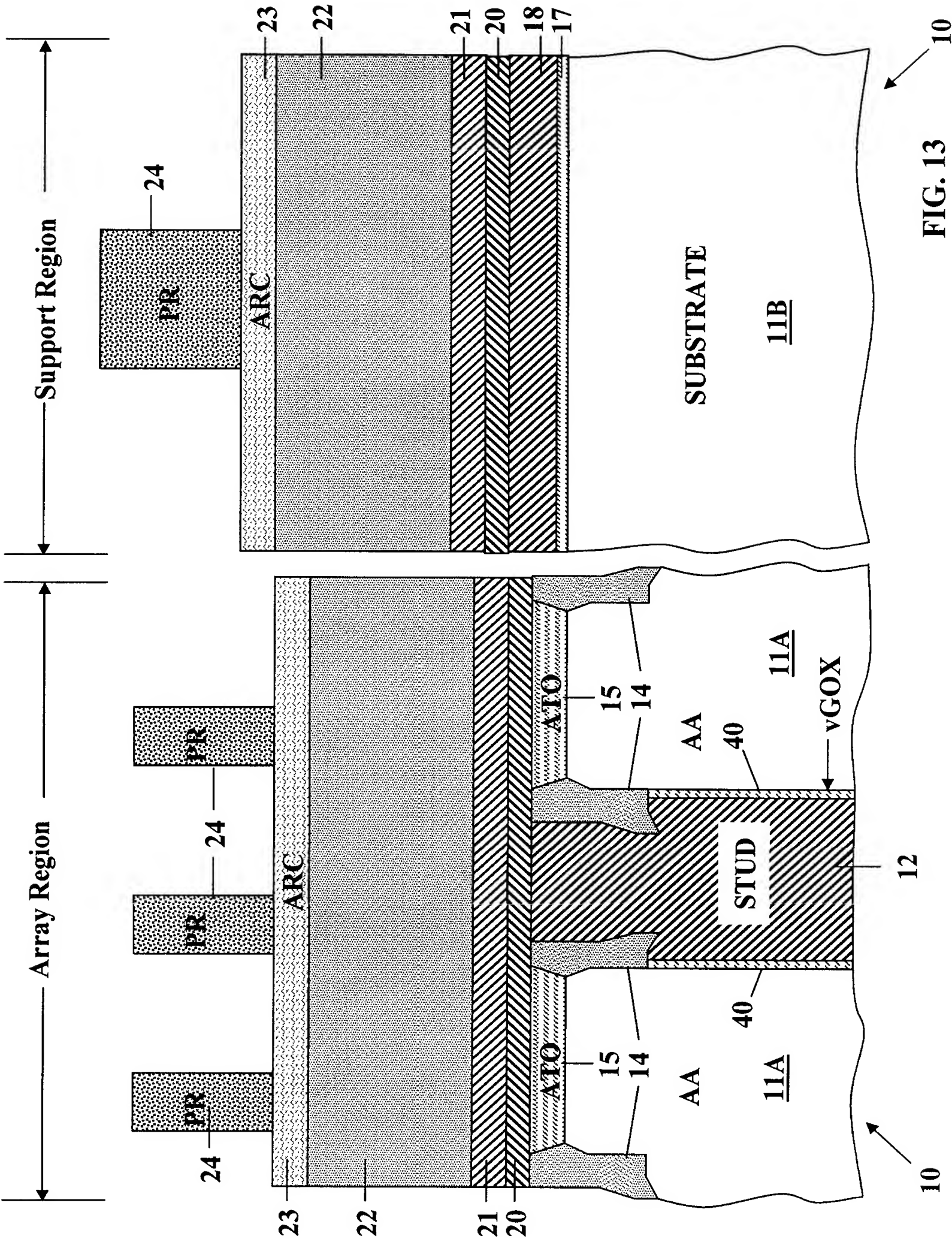


FIG. 13

# 11. HARD MASK OPEN

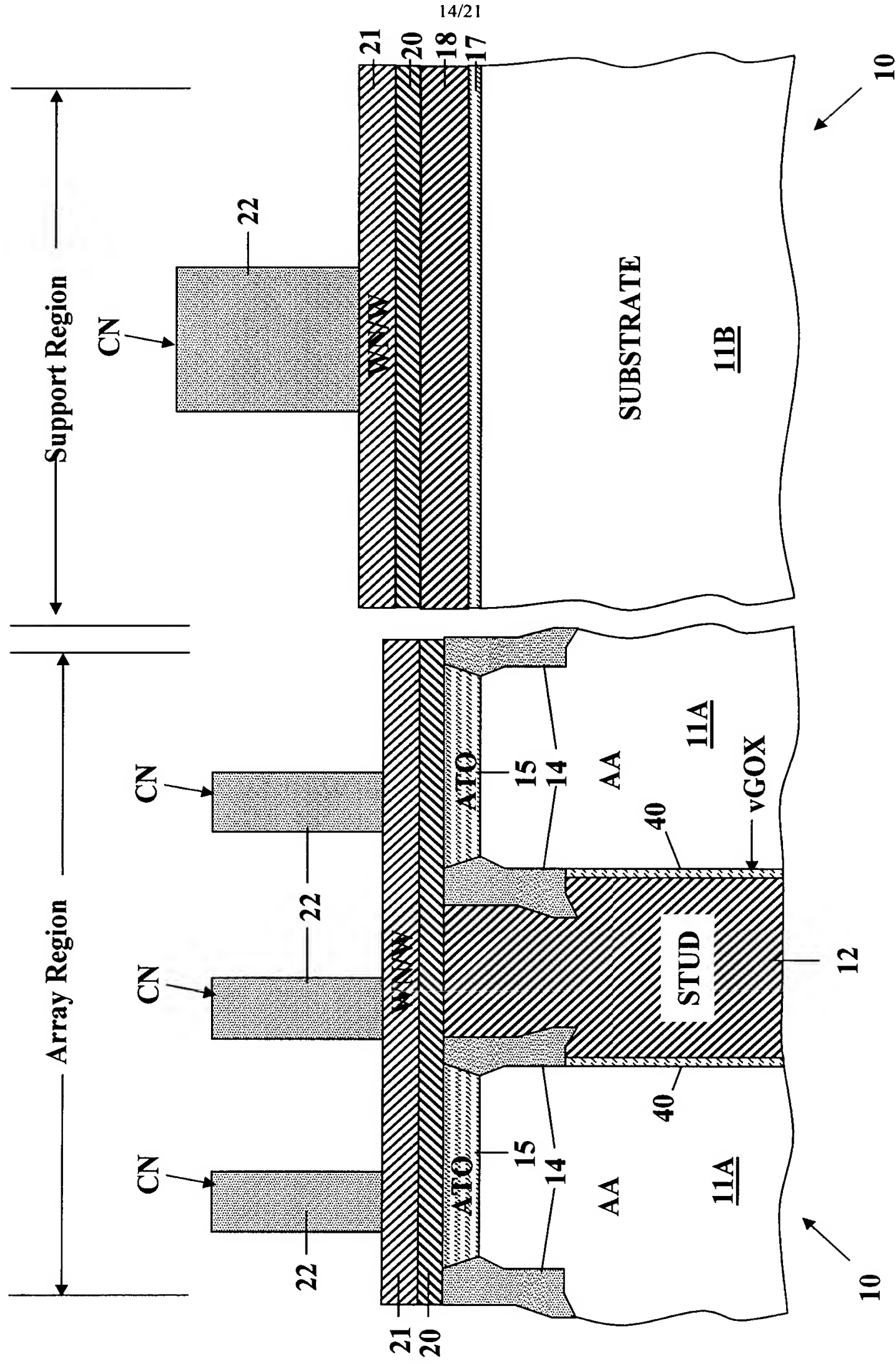


FIG. 14

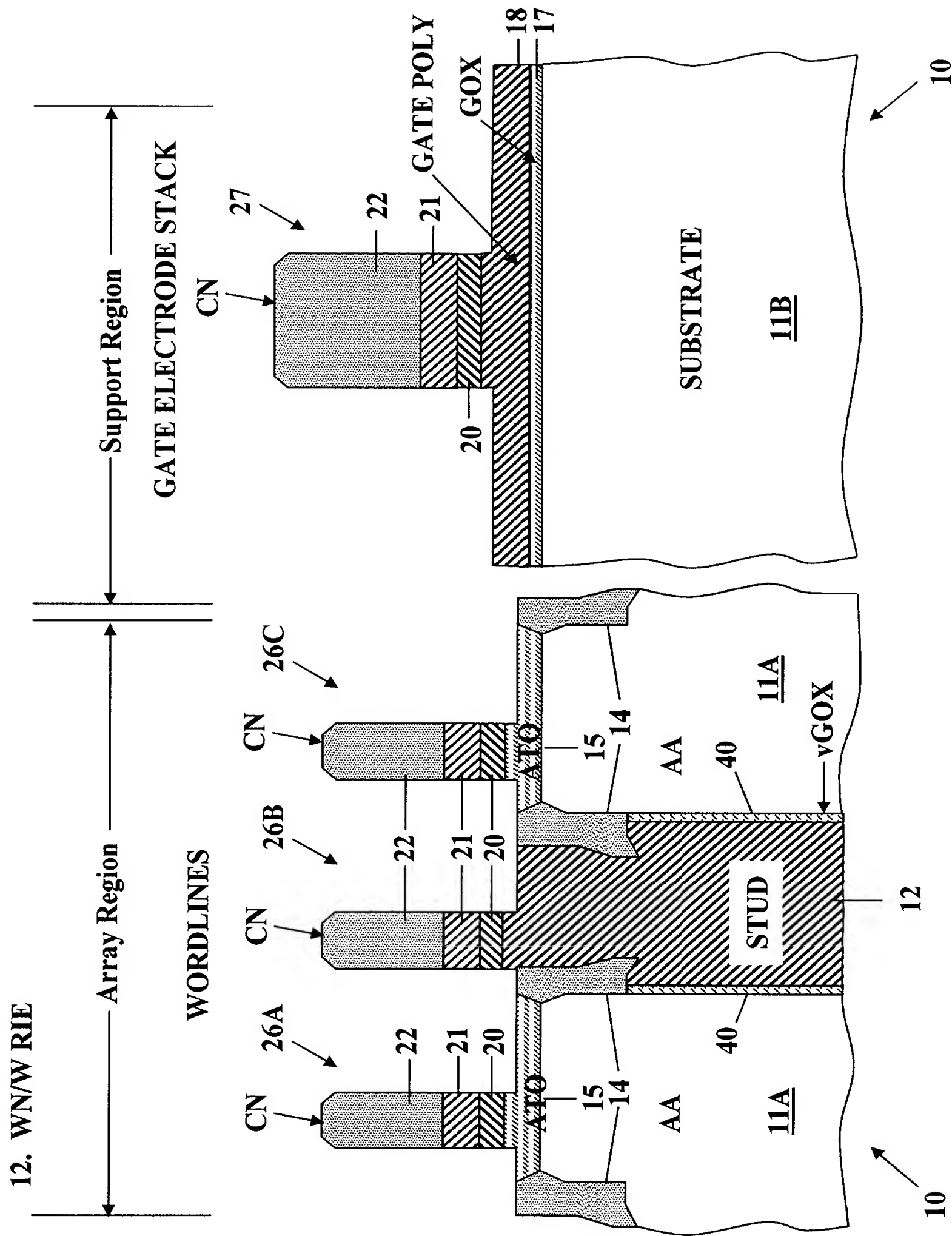


FIG. 15



13. ENCAPSULATING SPACER NITRIDE DEPOSITION

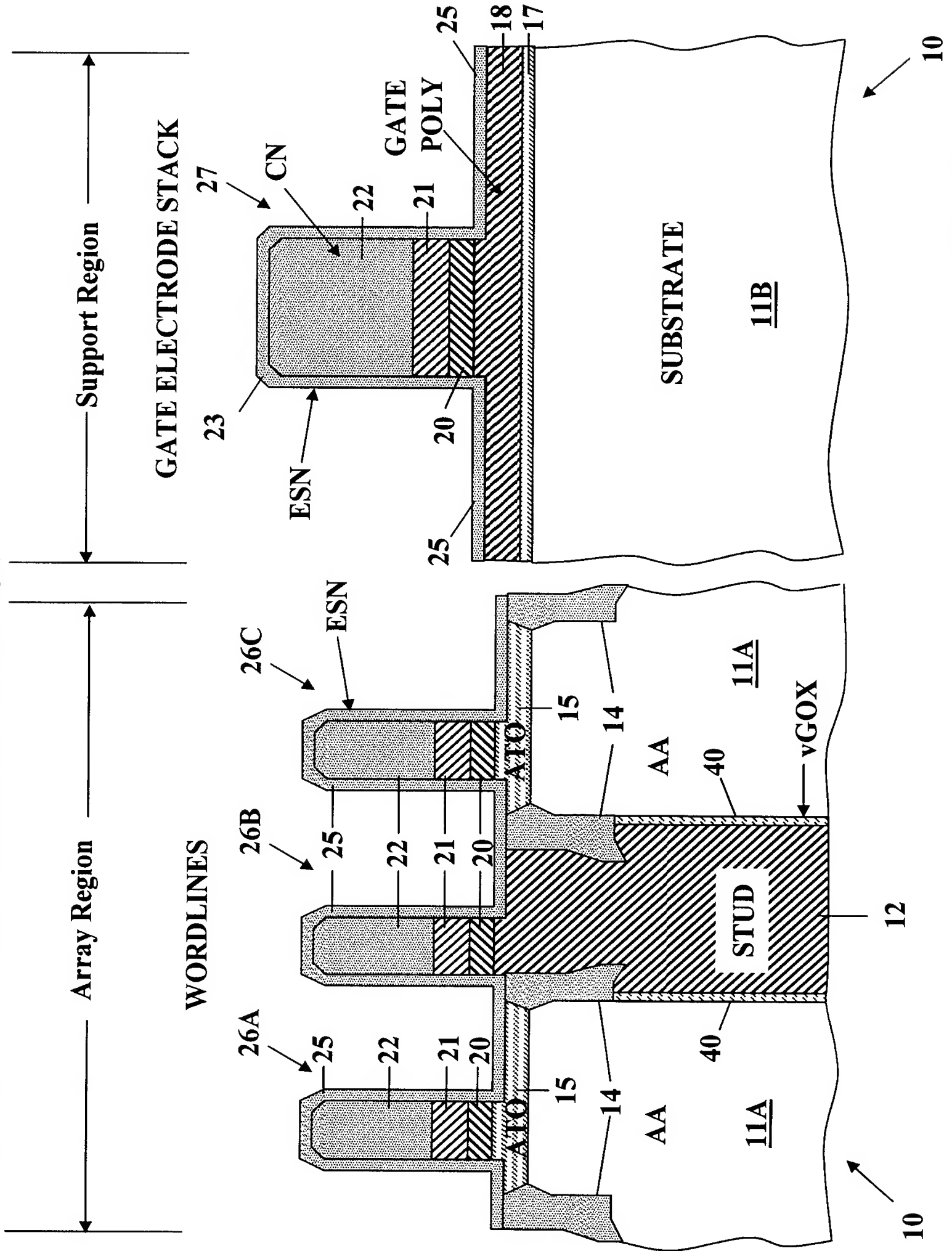
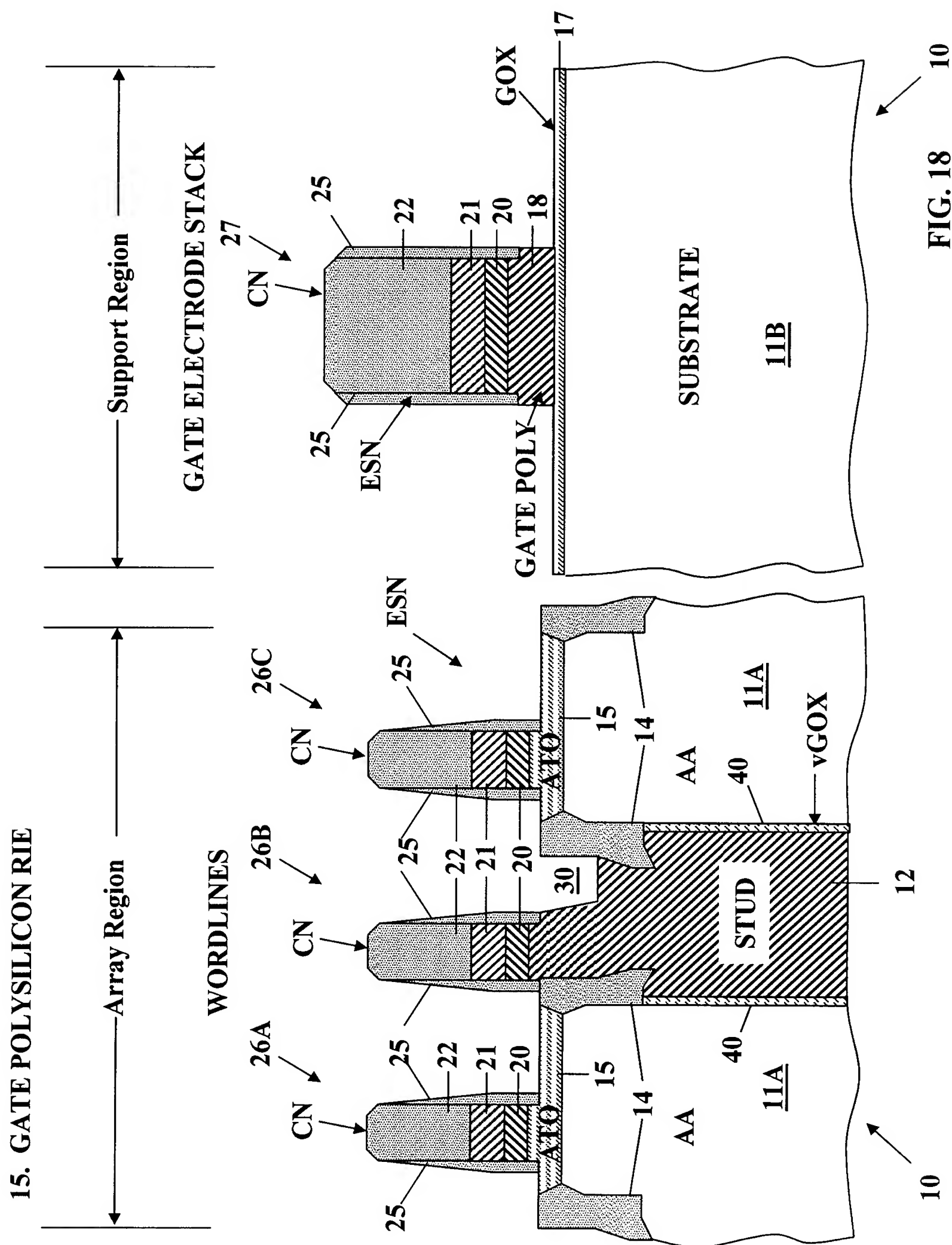


FIG. 16







SUPPORT PUNCH THROUGH

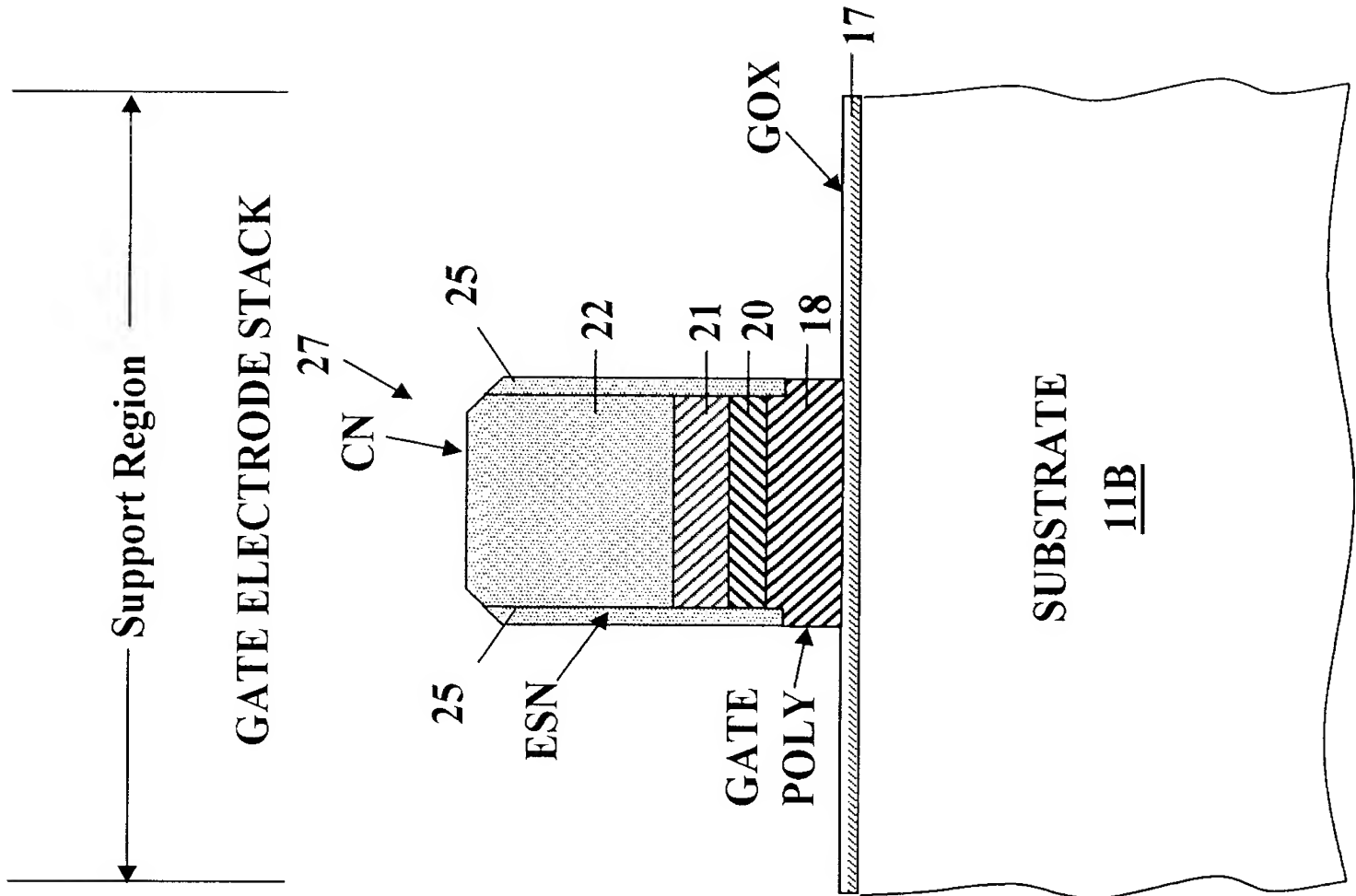
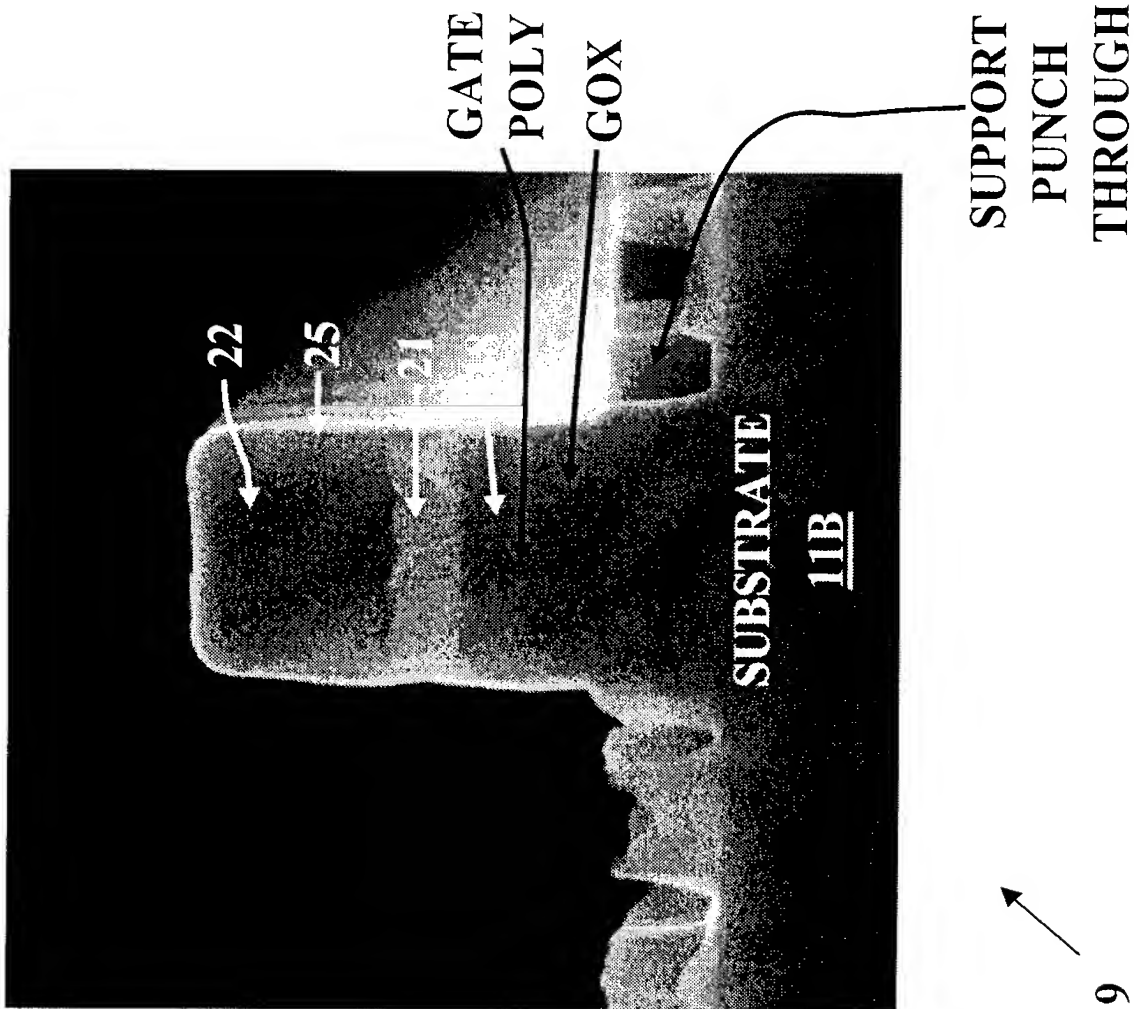


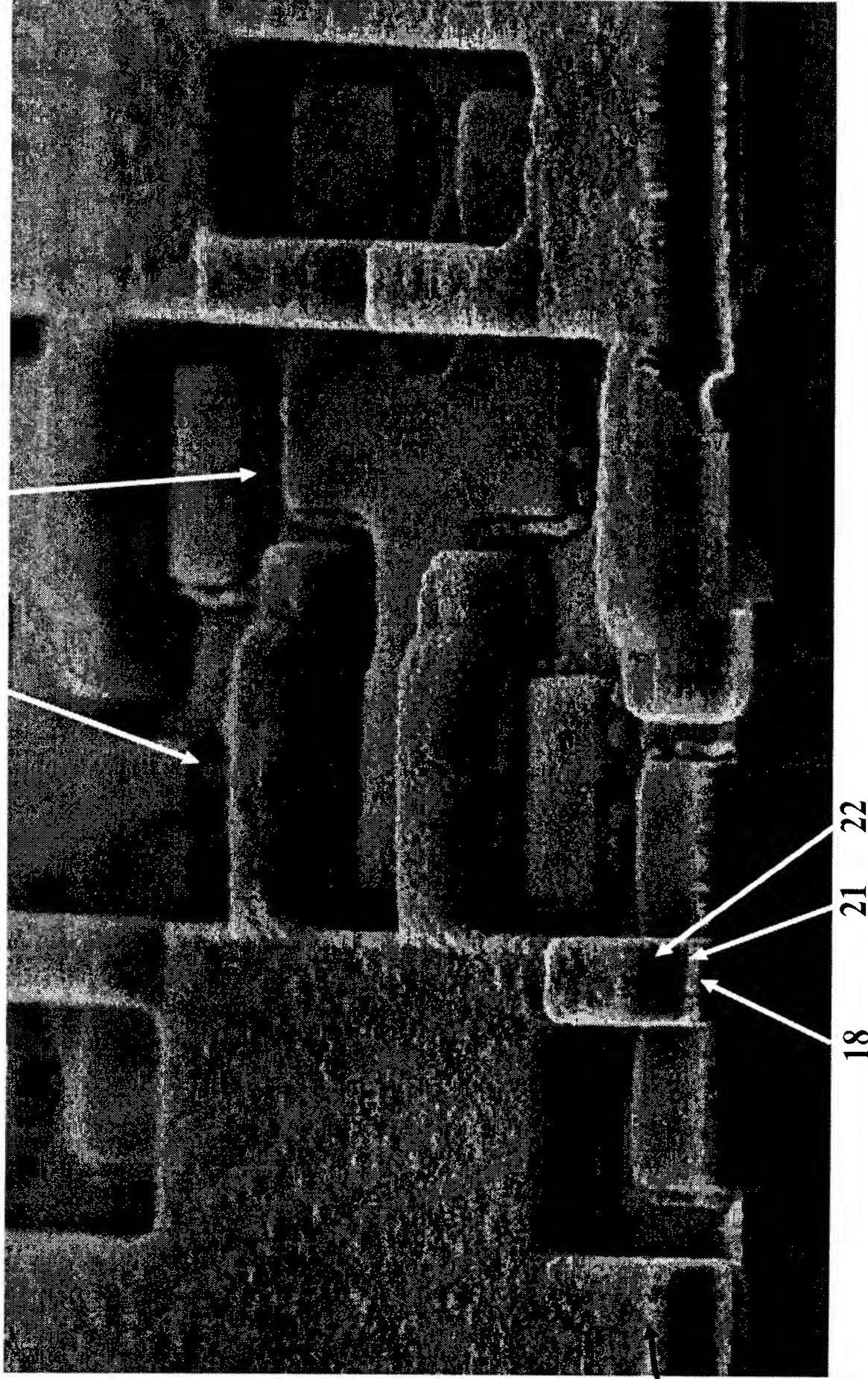
FIG. 19B



PRIOR ART

FIG. 19A

POLYSILICON RESIDUE LEFT BY  
INSUFFICIENT POLYSILICON OVERTCH  
DUE TO A SHORTER RIE



PRIOR ART

FIG. 20

Cr for decoration

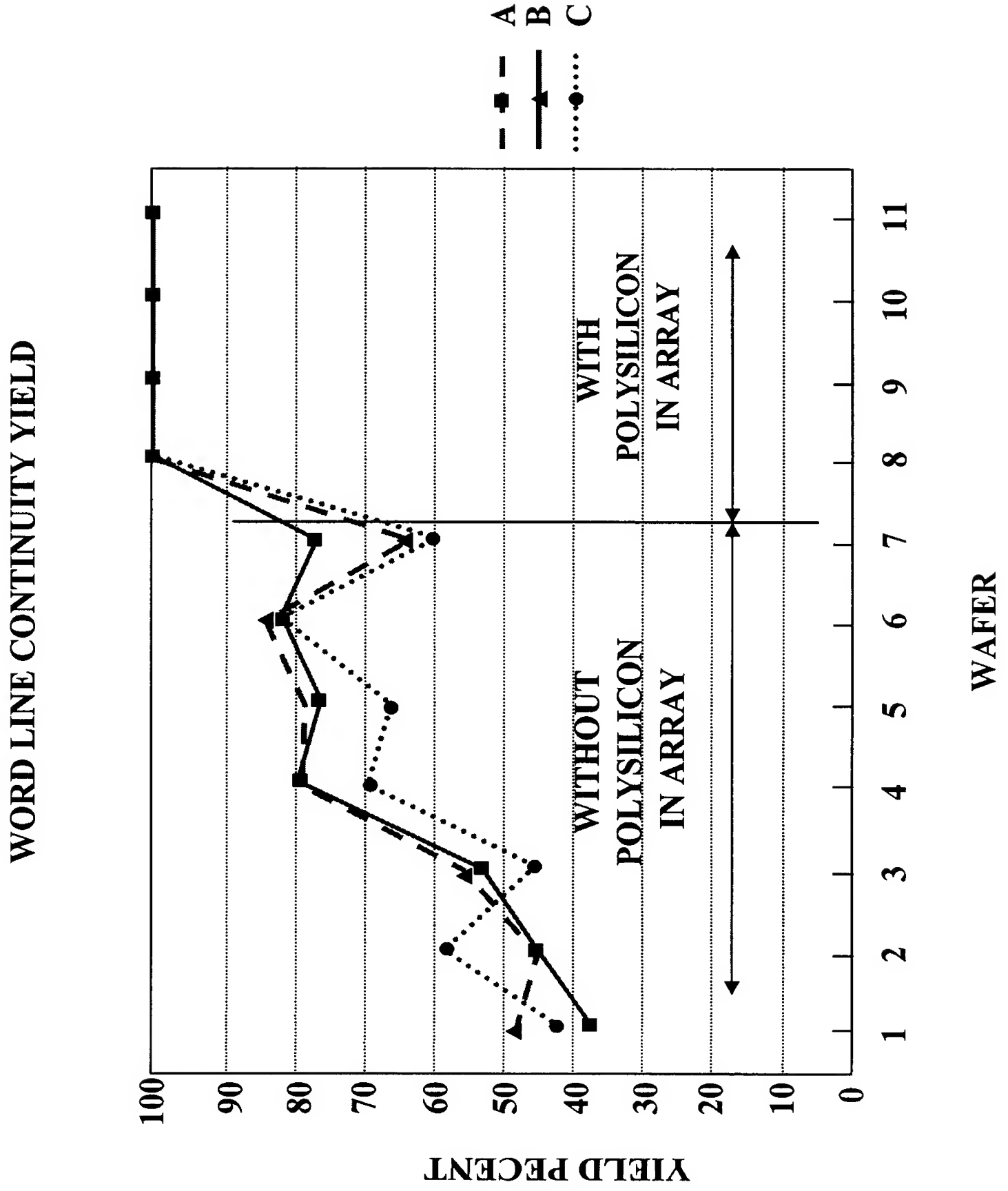


FIG. 21